

Title (en)  
MULTICHIP MODULE COMPRISING A PLURALITY OF SEMICONDUCTOR CHIPS AND PRINTED CIRCUIT BOARD COMPRISING A PLURALITY OF COMPONENTS

Title (de)  
MULTICHIPMODUL MIT MEHREREN HALBLEITERCHIPS SOWIE LEITERPLATTE MIT MEHREREN KOMPONENTEN

Title (fr)  
MODULE MULTIPUCES COMPORTANT PLUSIEURS PUCES DE SEMICONDUCTEUR ET CARTE DE CIRCUITS COMPORTANT PLUSIEURS COMPOSANTS

Publication  
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Application  
**EP 04726437 A 20040408**

Priority

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Abstract (en)  
[origin: WO2004093190A2] The invention relates to a multichip module comprising at least one first semiconductor chip (2) and at least one second semiconductor chip (3). Said semiconductor chips (2, 3) are arranged on or in a carrier medium (51) in a coplanar manner and respectively comprise corresponding components and contact surfaces (A1, A5) on the active upper sides thereof. At least one other semiconductor chip (3) comprises an arrangement of contact surfaces (A1, A5) which is mirror-inverted in relation to the first semiconductor chip (2). At least one first semiconductor chip (2) and at least one second semiconductor chip (3) are arranged adjacently and/or successively in such a way that the edges thereof which respectively have a corresponding arrangement of contact surfaces (A1, A5) are located opposite each other. Wirings (55, 56) extend between respectively opposite contact surfaces (A1, A5) and between contact surfaces (A1) located on the outer edges of the semiconductor chips (2, 3) and outer contacts (54).

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IPC 8 full level  
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